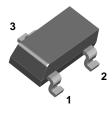
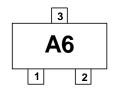
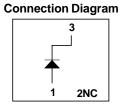


### **BAS16**







# **SOT-23**

## **Small Signal Diode**

**Absolute Maximum Ratings\*** 

T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{RRM}$	Maximum Repetitive Reverse Voltage	85	V
I <sub>F(AV)</sub>	Average Rectified Forward Current	200	mA
I <sub>FSM</sub>	Non-repetitive Peak Forward Surge Current Pulse Width = 1.0 second Pulse Width = 1.0 microsecond	1.0 2.0	A A
T <sub>stg</sub>	Storage Temperature Range	-55 to +150	°C
TJ	Operating Junction Temperature	-55 to +150	°C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

#### **Thermal Characteristics**

Symbol	Parameter	Value	Units
$P_{D}$	Power Dissipation	350	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

### Electrical Characteristics T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Max	Units
$V_R$	Breakdown Voltage	$I_R = 5.0 \mu A$	85		V
V <sub>F</sub>	Forward Voltage	$I_F = 1.0 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 50 \text{ mA}$ $I_F = 150 \text{ mA}$		715 855 1.0 1.25	mV mV V
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 75 V V <sub>R</sub> = 25 V, T <sub>A</sub> = 150°C V <sub>R</sub> = 75 V, T <sub>A</sub> = 150°C		1.0 30 50	μΑ μΑ μΑ
C <sub>T</sub>	Total Capacitance	V <sub>R</sub> = 0, f = 1.0 MHz		2.0	pF
t <sub>rr</sub>	Reverse Recovery Time	$I_F = I_R = 10 \text{ mA}, I_{RR} = 1.0 \text{ mA},$ $R_L = 100 \Omega$		6.0	ns

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NOTES:

1) These ratings are based on a maximum junction temperature of 150 degrees C.

2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### **Small Signal Diode**

(continued)

### **Typical Characteristics**

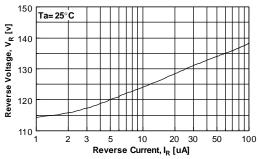


Figure 1. Reverse Voltage vs Reverse Current BV - 1.0 to 100 uA

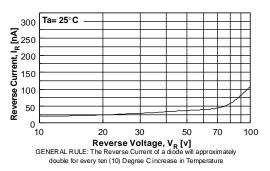


Figure 2. Reverse Current vs Reverse Voltage IR - 10 to 100 V

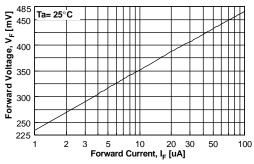


Figure 3. Forward Voltage vs Forward Current VF - 1.0 to 100 uA

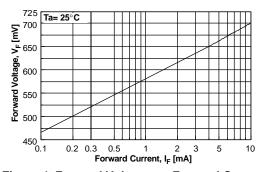


Figure 4. Forward Voltage vs Forward Current VF - 0.1 to 10 mA

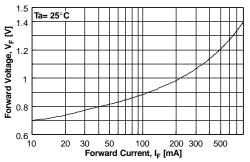


Figure 5. Forward Voltage vs Forward Current VF - 10 - 800 mA

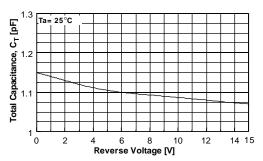


Figure 6. Total Capacitance

### **Small Signal Diode**

(continued)

### Typical Characteristics (continued)

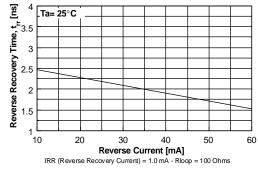


Figure 7. Reverse Recovery Time vs Reverse Current TRR - IR 10 mA vs 60 mA

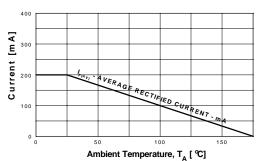
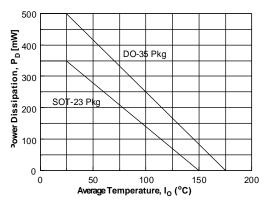


Figure 8. Average Rectified Current (IF(AV)) versus Ambient Temperature (TA)



Figrue 9. Power Derating Curve

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